



Patent Application No. 10/613,989

Applicant: YAMASAKI et al.

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TC/AU: 3725

Examiner: L. Larson

Docket No.: 402698

Customer No.: 23548

Commissioner for Patents
U.S. Patent and Trademark Office
Customer Service Window, Mail Stop Amendment
Randolph Building
401 Dulany Street
Alexandria, VA 22314

REPLY TO OFFICE ACTION

Sir:

In reply to the Office Action dated September 27, 2005, Applicants petition for a one-month extension of time, submit the requisite fee therefor, and request that the referenced patent application be amended as shown below.

Amendments to the Title are on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 3 of this paper.

Remarks/Arguments begin on page 6 of this paper.

01/30/2006 HAL111 00000068 121216 10613989
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AMENDMENTS TO THE TITLE

Replace the title with:

LEADMETHOD OF FORMING~~FOR~~ LEADS OF
A SEMICONDUCTOR DEVICE